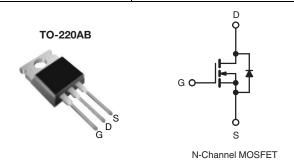


Vishay Siliconix

### **Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	500			
R <sub>DS(on)</sub> (Ω)	V <sub>GS</sub> = 10 V 0.85			
Q <sub>g</sub> (Max.) (nC)	39			
Q <sub>gs</sub> (nC)	10			
Q <sub>gd</sub> (nC)	19			
Configuration	Single			



### **FEATURES**

- Ultra Low Gate Charge
- Reduced Gate Drive Requirement
- Enhanced 30 V V<sub>GS</sub> Rating
- Reduced C<sub>iss</sub>, C<sub>oss</sub>, C<sub>rss</sub>
- Extremely High Frequency Operation
- Repetitive Avalanche Rated
- Compliant to RoHS Directive 2002/95/EC



This new series of low charge Power MOSFETs achieve significantly lower gate charge over conventional MOSFETs. Utilizing the new LCDMOS technology, the device improvements are achieved without added product cost, allowing for reduced gate drive requirements and total system savings. In addition, reduced switching losses and improved efficiency are achievable in a variety of high frequency applications. Frequencies of a few MHz at high current are possible using the new low charge MOSFETs.

These device improvements combined with the proven ruggedness and reliability that are characteristic of Power MOSFETs offer the designer a new standard in power transistors for switching applications.

ORDERING INFORMATION		
Package	TO-220AB	
Lead (Pb)-free	IRF840LCPbF	
Lead (Fb)-life	SiHF840LC-E3	
SnPb	IRF840LC	
SIFD	SiHF840LC	

ABSOLUTE MAXIMUM RATINGS ( $T_{\mbox{\scriptsize C}}$	= 25 °C, unless otherwis	se noted)			
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	500	V	
Gate-Source Voltage		$V_{GS}$	± 30	1 v	
Continuous Drain Current	$V_{GS}$ at 10 V $T_C = 25 ^{\circ}\text{C}$	,	8.0	А	
Continuous Drain Current	$V_{GS}$ at 10 $V_{C} = 100 ^{\circ}C$	I <sub>D</sub>	5.1		
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	28	1	
Linear Derating Factor			1.0	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>		E <sub>AS</sub>	510	mJ	
Repetitive Avalanche Current <sup>a</sup>		I <sub>AR</sub>	8.0	Α	
Repetitive Avalanche Energy <sup>a</sup>		E <sub>AR</sub>	13	mJ	
Maximum Power Dissipation $T_C = 25  ^{\circ}C$		$P_{D}$	125	W	
Peak Diode Recovery dV/dtc		dV/dt	3.5	V/ns	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature) for 10 s			300 <sup>d</sup>	7	
Mounting Torque	6 20 or M2 corour		10	lbf ⋅ in	
	6-32 or M3 screw		1.1	N⋅m	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b.  $V_{DD} = 50 \text{ V}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ ,  $L = 14 \,^{\circ}\text{mH}$ ,  $R_g = 25 \,^{\circ}\Omega$ ,  $I_{AS} = 8.0 \,^{\circ}\text{A}$  (see fig. 12).
- c.  $I_{SD} \le 8.0$  A,  $dI/dt \le 100$  A/ $\mu$ s,  $V_{DD} \le V_{DS}$ ,  $T_{J} \le 150$  °C.
- d. 1.6 mm from case.

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply

# IRF840LC, SiHF840LC

# Vishay Siliconix



THERMAL RESISTANCE				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.50	-	°C/W
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	1.0	

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub>	= 0 V, I <sub>D</sub> = 250 μA	500	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.63	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> :	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I <sub>GSS</sub>		V <sub>GS</sub> = ± 20 V	ı	-	± 100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		= 500 V, V <sub>GS</sub> = 0 V /, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	25 250	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 4.8 A <sup>b</sup>	-	-	0.85	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 50 V, I <sub>D</sub> = 4.8 A <sup>b</sup>	4.0	-	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	1100	-	
Output Capacitance	C <sub>oss</sub>	1	$V_{DS} = 25 \text{ V},$		170	-	pF
Reverse Transfer Capacitance	$C_{rss}$	] f = 1	.0 MHz, see fig. 5	-	18	-	
Total Gate Charge	Qg			-	-	39	
Gate-Source Charge	$Q_{gs}$	V <sub>GS</sub> = 10 V	$I_D = 8.0 \text{ A}, V_{DS} = 400 \text{ V}$ see fig. 6 and 13 <sup>b</sup>	ı	-	10	nC
Gate-Drain Charge	$Q_{gd}$		and high a minum to	i	-	19	
Turn-On Delay Time	t <sub>d(on)</sub>			ı	12	-	
Rise Time	t <sub>r</sub>		$= 250 \text{ V}, I_D = 8.0 \text{ A},$	ı	25	-	nc
Turn-Off Delay Time	$t_{d(off)}$	R <sub>g</sub> =	= 9.1 Ω, $R_D$ = 30 Ω see fig. 10 <sup>b</sup>	ı	27	-	ns
Fall Time	t <sub>f</sub>			-	19	-	
Internal Drain Inductance	$L_D$	Between lead 6 mm (0.25")	from	-	4.5	-	m1.1
Internal Source Inductance	L <sub>S</sub>	package and die contact	center of	-	7.5	-	- nH
Drain-Source Body Diode Characteristic	s					•	
Continuous Source-Drain Diode Current	I <sub>S</sub>	showing the	MOSFET symbol showing the		-	8.0	^
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>	integral revers p - n junction	7 1	-	-	28	- A
Body Diode Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C	C, I <sub>S</sub> = 8.0 A, V <sub>GS</sub> = 0 V <sup>b</sup>	-	-	2.0	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	T <sub>1</sub> =	25 °C, I <sub>F</sub> = 8.0 A,	-	490	740	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	dl	/dt = 100 A/µs <sup>b</sup>	-	3.0	4.5	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic tu	rn-on time is negligible (turn	on is dor	minated b	ov Le and	Ln)

### **Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. Pulse width  $\leq$  300 µs; duty cycle  $\leq$  2 %.



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

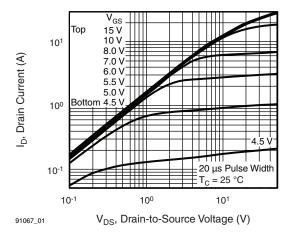


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

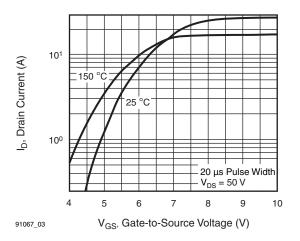


Fig. 3 - Typical Transfer Characteristics

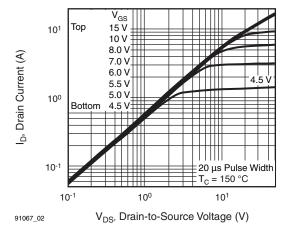


Fig. 2 - Typical Output Characteristics, T<sub>C</sub> = 150 °C

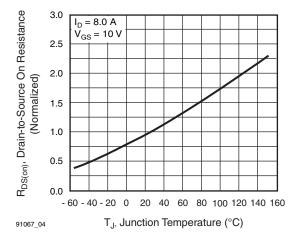
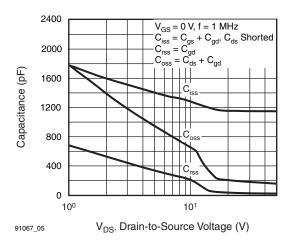


Fig. 4 - Normalized On-Resistance vs. Temperature

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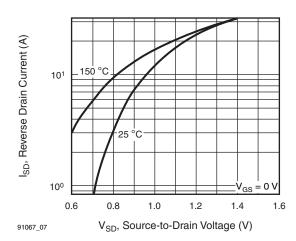
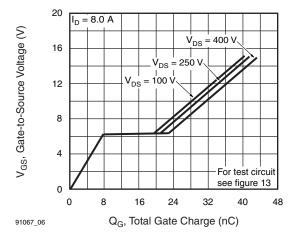


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 7 - Typical Source-Drain Diode Forward Voltage



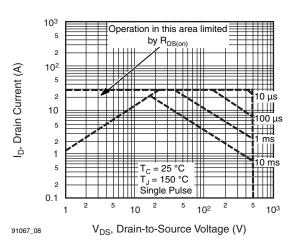


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

Fig. 8 - Maximum Safe Operating Area



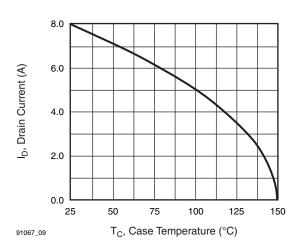


Fig. 9 - Maximum Drain Current vs. Case Temperature

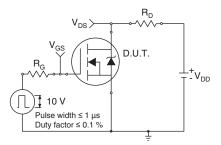


Fig. 10a - Switching Time Test Circuit

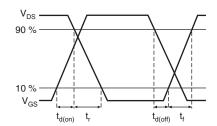


Fig. 10b - Switching Time Waveforms

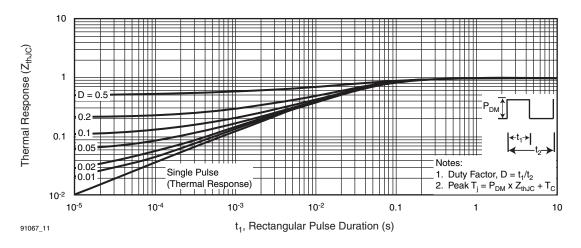


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

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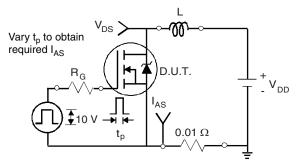


Fig. 12a - Unclamped Inductive Test Circuit

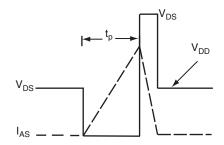


Fig. 12b - Unclamped Inductive Waveforms

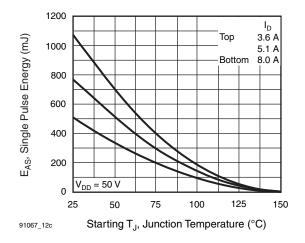


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

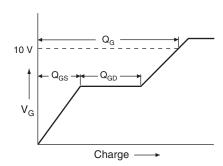


Fig. 13a - Basic Gate Charge Waveform

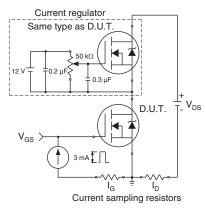
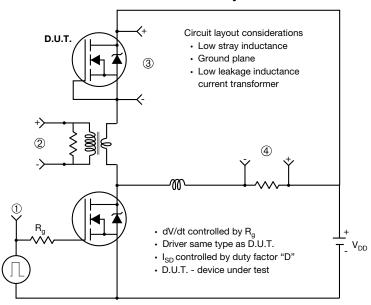


Fig. 13b - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



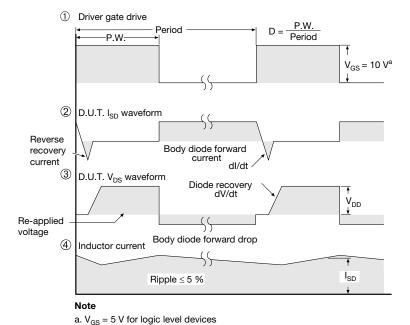


Fig. 14 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91067.





## TO-220-1



DIM.	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

### Note

 $\bullet$   $M^{\star}=0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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